Application No.: 10/535,266 MAT-8684US

Amendment Dated: January 9, 2009
Reply to Office Action of: October 9, 2008

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

 (Currently Amended) A method of manufacturing a plasma display device having a panel in which a pair of substrates having transparency at least on a front side, the substrates being oppositely disposed so that <u>a_discharge</u> space and discharge cells are formed between the substrates, and a metallic holding plate that supports the panel via a thermal conductive material, the holding-plate having-an outer-edge, the method comprising:

forming the thermal conductive material from a pull-to-remove type adhesive;

applying the adhesive to one of the panel and the holding plate;

forming a groove, in which a portion of the adhesive flows, at a periphery of the holding plate;

bonding the panel to the holding plate together; and

curing the adhesive by simultaneous application of pressure and heat,

wherein the groove (i) is positioned between a groove in which a portion of the adhesive flows and is formed at a periphery and the outer-edge-of the holding plate, the groove accepting and (ii) has dimensions sufficient for preventing—the portion of the flowed adhesive and preventing it from leaking to the outside of the holding plate from reaching the outer-edge of the holding plate when the panel and the holding plate are bonded together.

2.-12. (Cancelled).

13. (Original) The method of manufacturing the plasma display device of Claim 1, wherein a driving circuit block containing a semiconductor device for feeding a display signal to the panel is mounted on a cooling plate on a back side of the 10/535.266 MAT-8684US

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holding plate, a portion of the thermal conductive material is exposed from the holding plate, and the driving circuit block-mounted cooling plate is bonded with the exposed portion of the thermal conductive material.

(Original) The method of manufacturing the plasma display device of Claim 1, wherein a driving circuit block containing a semiconductor device for feeding a display signal to the panel is mounted on a cooling plate on a back side of the holding plate, a portion of the thermal conductive material is extended to the driving circuit block-mounted cooling plate.

15.-17. (Cancelled).

(New) A method of dismounting a plasma display device having a panel in which a pair of substrates having transparency at least on a front side, the substrates being oppositely disposed so that a discharge space and discharge cells are formed between the substrates, and a metallic holding plate that supports the panel via a thermal conductive material,

wherein the thermal conductive material is formed of a pull-to-remove type adhesive, and includes an exposed section of the adhesive a part of which bulges out between the panel and the holding plate,

the method comprising the steps of:

pulling out the exposed section of the adhesive for lowering adhesive force of the pull-to-remove type adhesive; and

separating the panel from the holding plate.